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ITEM NO.	Description	Material
1	LS-BGA63C-B-61 Substrate	High Temp FR4
2	Terminal Pin	Brass-PS-2

FRONT VIEW

Description: Giga-snaP BGA SMT Land Socket

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ± 0.0254 mm [± 0.001 "], Pitches (from true position) ± 0.0254 mm [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances ± 0.127 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

Doc Rev	Date	Initials	Description
Α	06/24/14	DH	Original

LS-BGA63C-61 Drawing

Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodélectronics.com Material: N/A Finish: N/A Weight: 0.31

STAT	US: Relea	ased	SHEET: 1 OF 1	REV. A
ENG:	M.A. Fed	de	DRAWN BY: D. Hauer	SCALE: 5:1
FILE:	LS-BGA6	3C-61	DATE: 06/24/14	